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United States Design Patent

Tsukamoto et al.

(10)

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(45)

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(54) SEMICONDUCTOR MODULE

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(73) Assignee: ROHM CO., LTD., Kyoto (JP)

(**) Term: 15 Years

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(30) Foreign Application Priority Data

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USPC D13/182

(58) Field of Classification Search
USPC D13/123, 154, 173, 178, 182, 184, 199;
D15/144, 144.1, 199
CPC .. H01M 10/46; H01M 10/425; H01M 2/1022;
H01R 24/00; H01R 12/592; H01R
4/2433; H01R 112/716; H01R 13/6461;
H01R 13/506; H01R 13/639; H01R
13/5837; H01R 13/6594; H01R 13/16582;
H02J 7/0003; H02J 7/0013; H02J 7/044;
H02J 7/0045; H02J 201/006; H05B
3/143; H01L 21/02; H01L 21/64; H01L
21/67; H01L 21/68; C30B 25/10; C23C
16/44;

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(57) CLAIM

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor module showing our new design;

FIG. 2 is a rear, bottom and left side perspective view thereof;

FIG. 3 is a front view thereof, the rear view being a mirror image of FIG. 3;

FIG. 4 is a top plan view thereof;

FIG. 5 is a bottom plan view thereof;

FIG. 6 is a right side view thereof;

FIG. 7 is a left side view thereof;

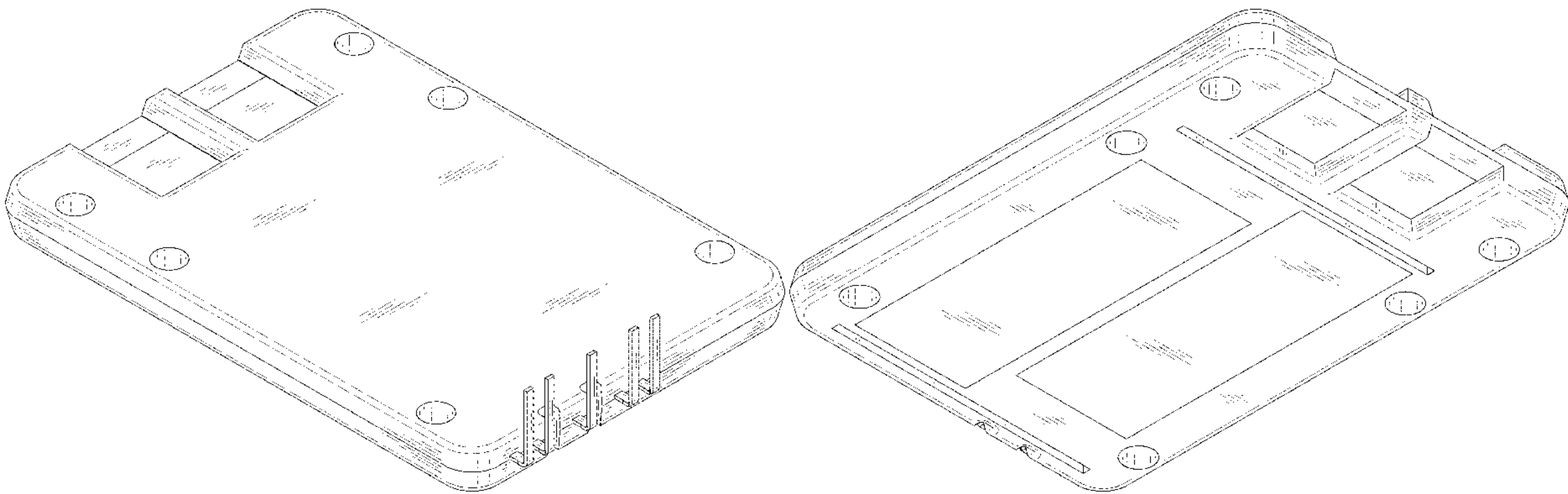
FIG. 8 is a cross-sectional view taken along line 8-8 in FIG. 5 thereof;

FIG. 9 is a cross-sectional view taken along line 9-9 in FIG. 5 thereof;

FIG. 10 is a cross-sectional view taken along line 10-10 in FIG. 5 thereof; and,

FIG. 11 is a cross-sectional view taken along line 11-11 in FIG. 5 thereof.

1 Claim, 8 Drawing Sheets



(58) **Field of Classification Search**
CPC . C23C 16/45; C23C 16/4582; C23C 16/4583;
C23C 16/4586
See application file for complete search history.

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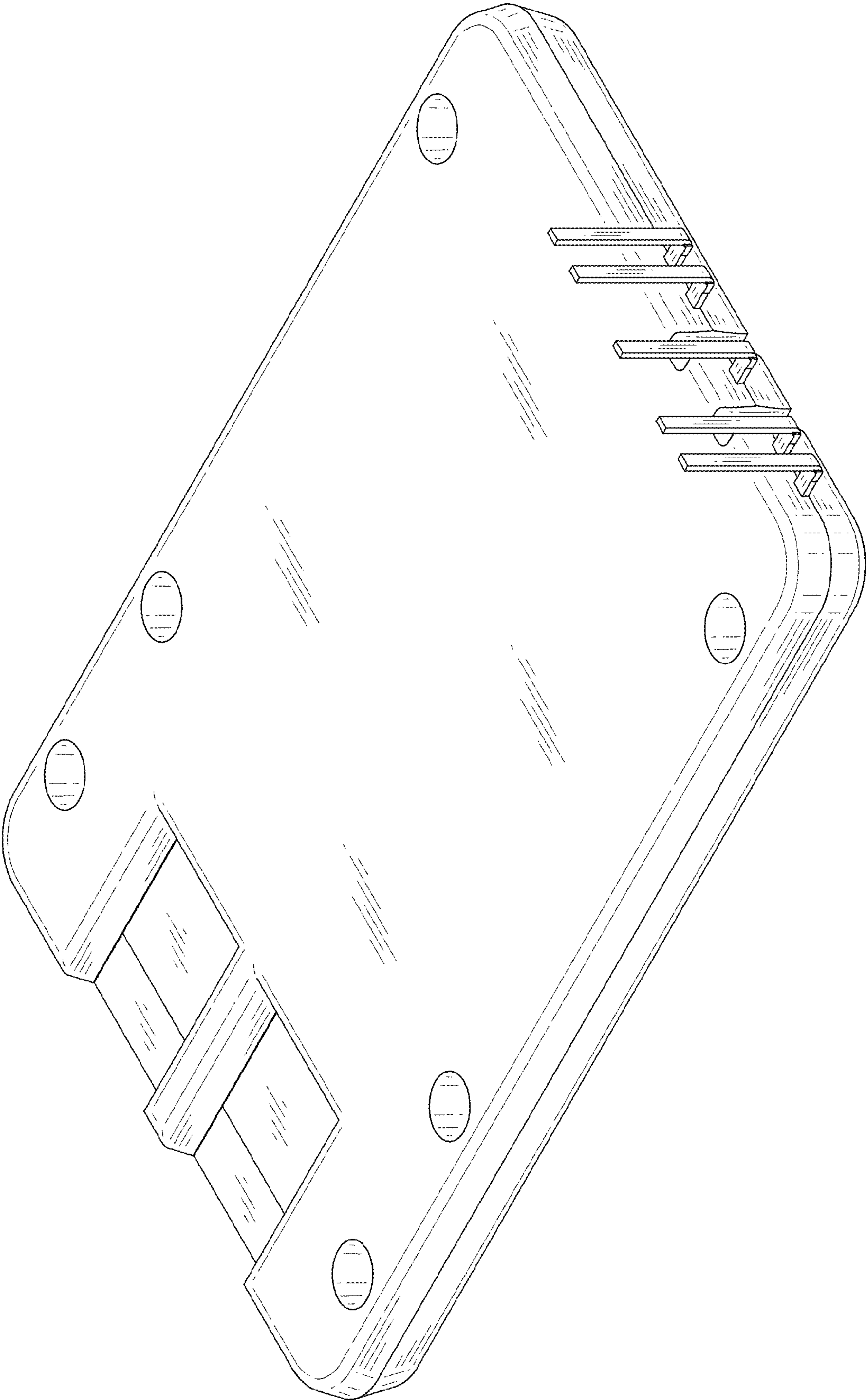


FIG.1

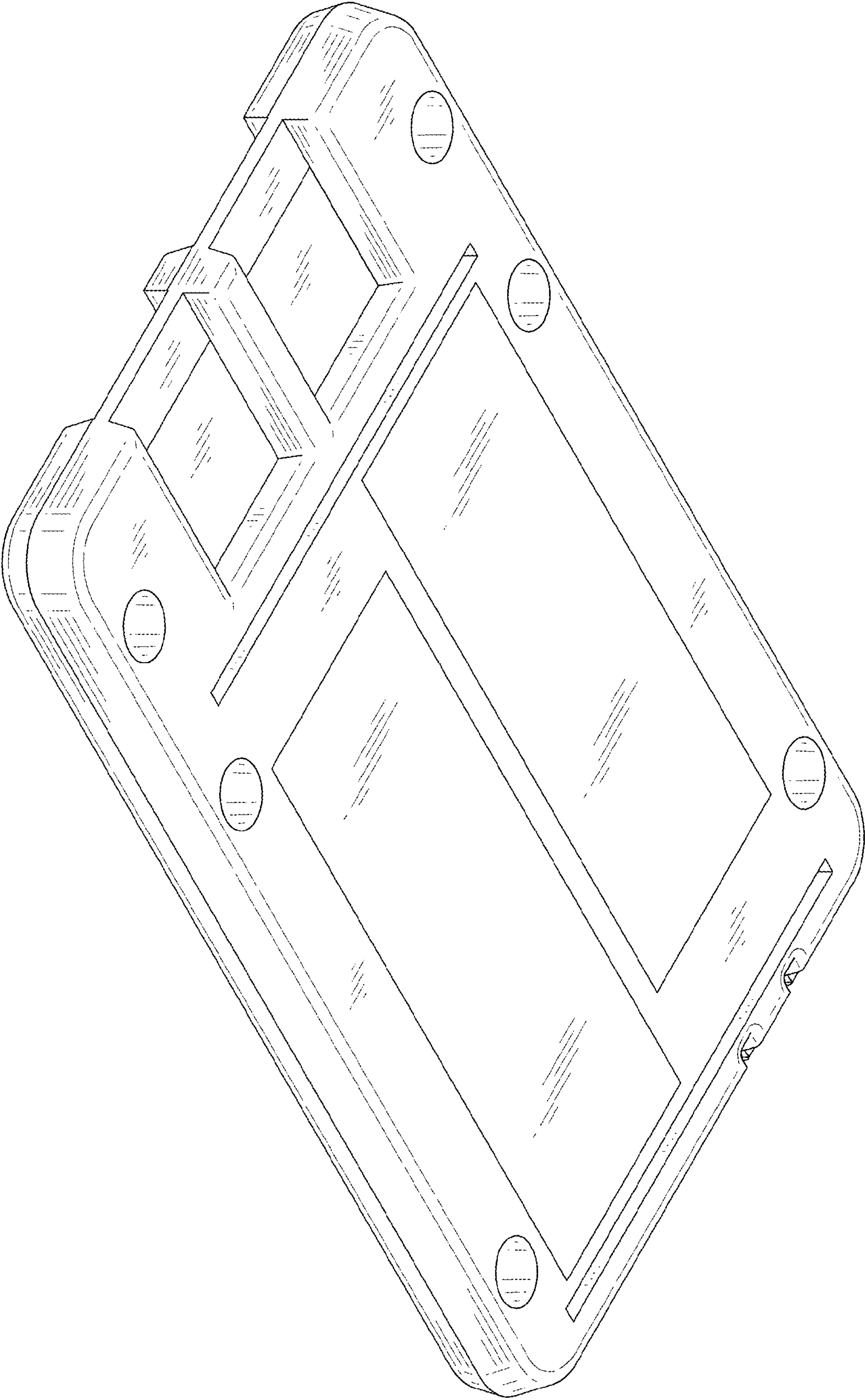


FIG.2

FIG.3

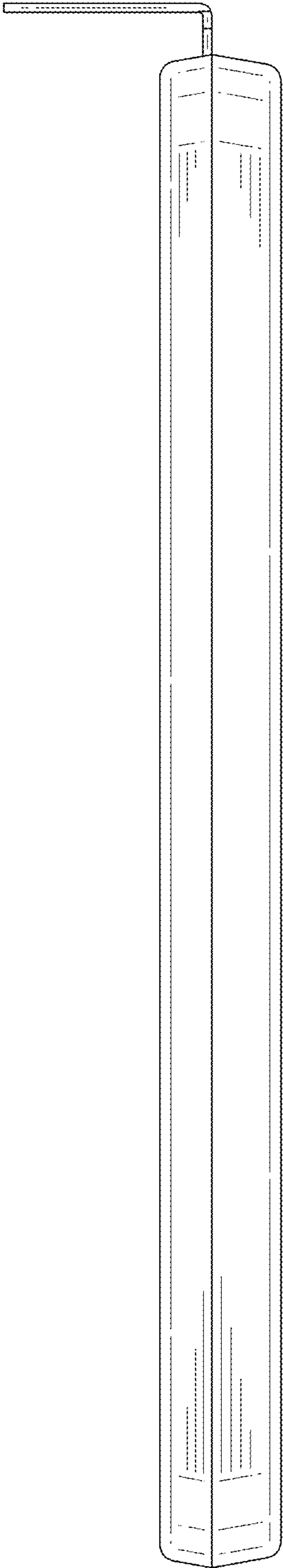


FIG.4

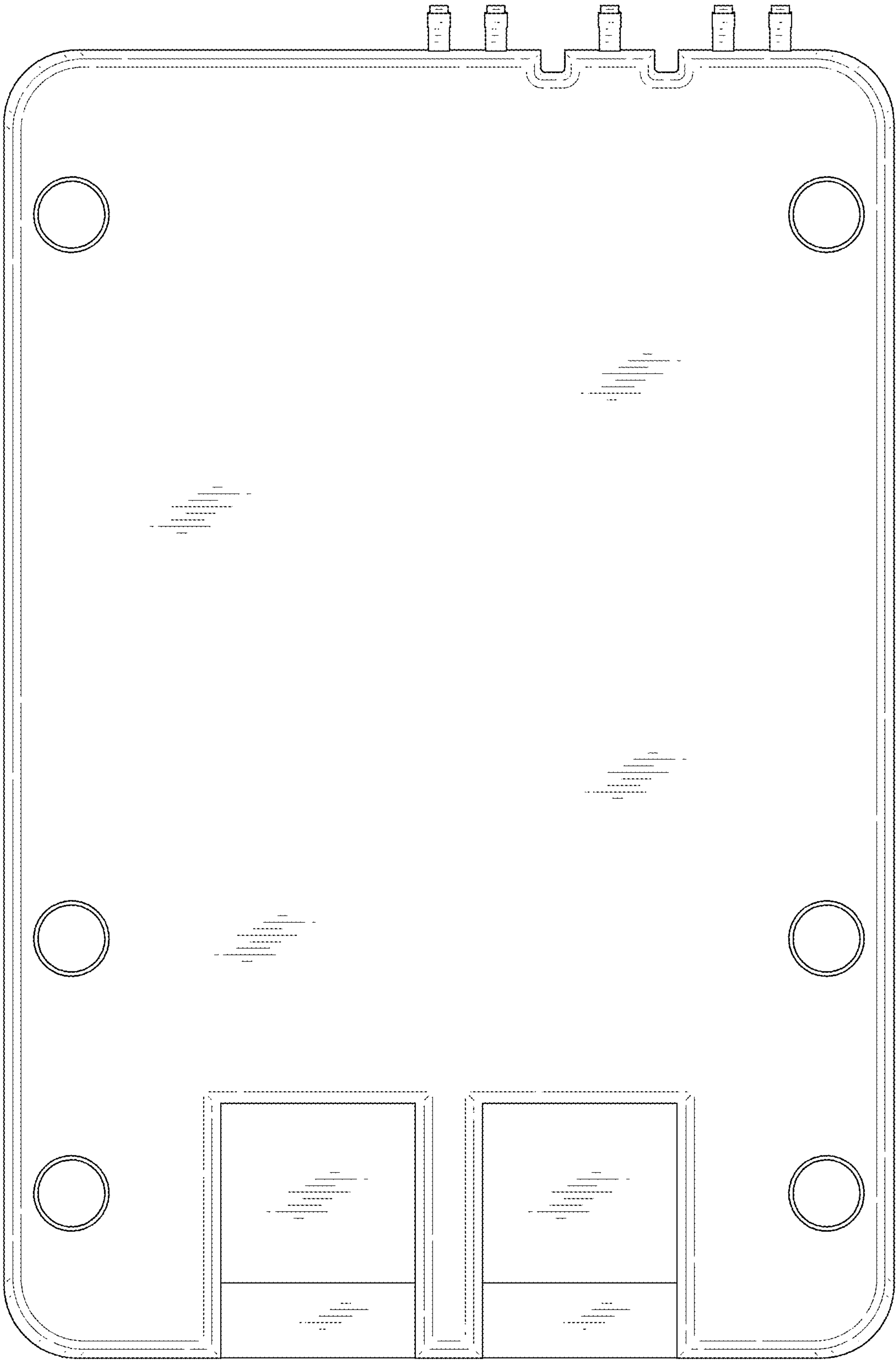


FIG.5

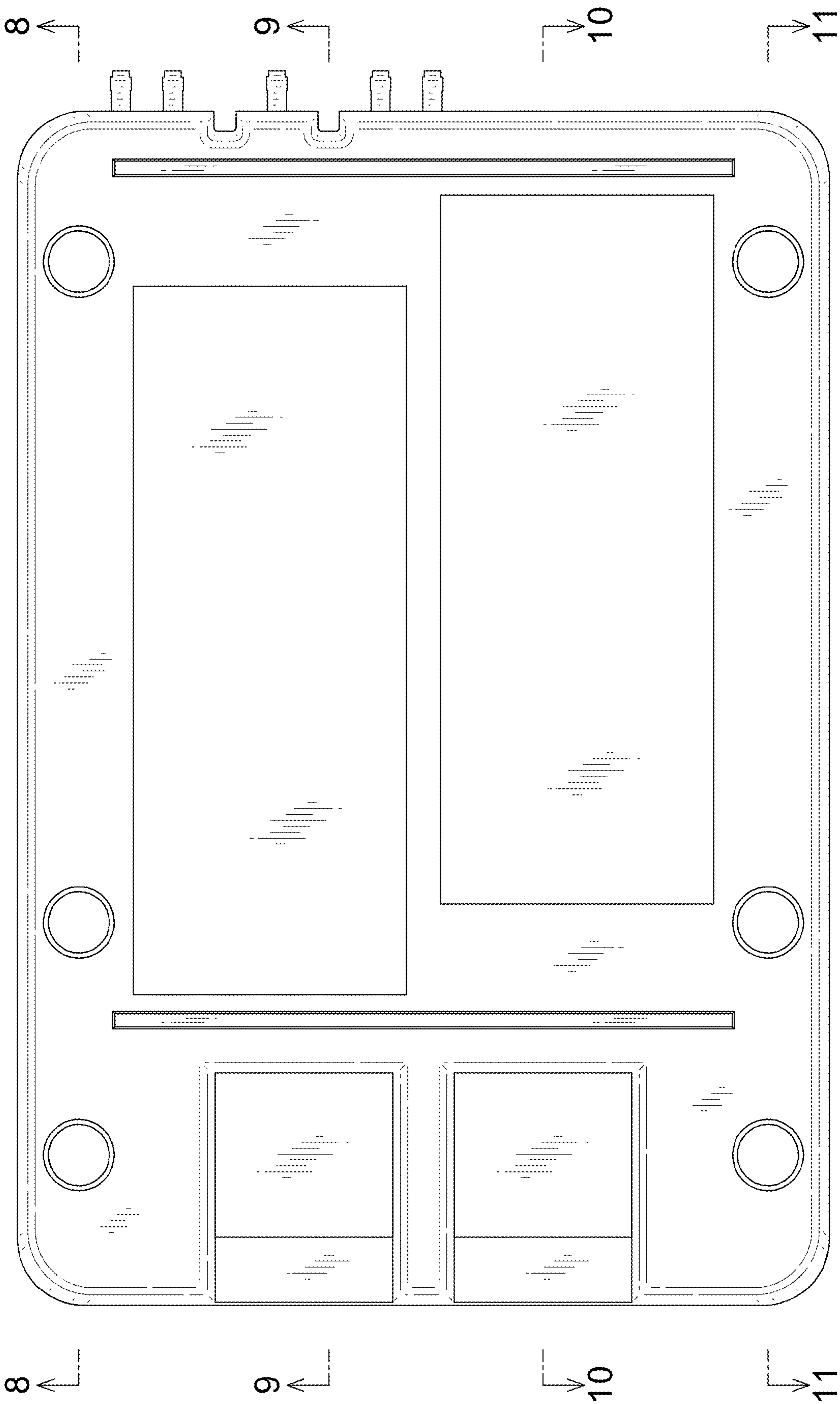


FIG.6

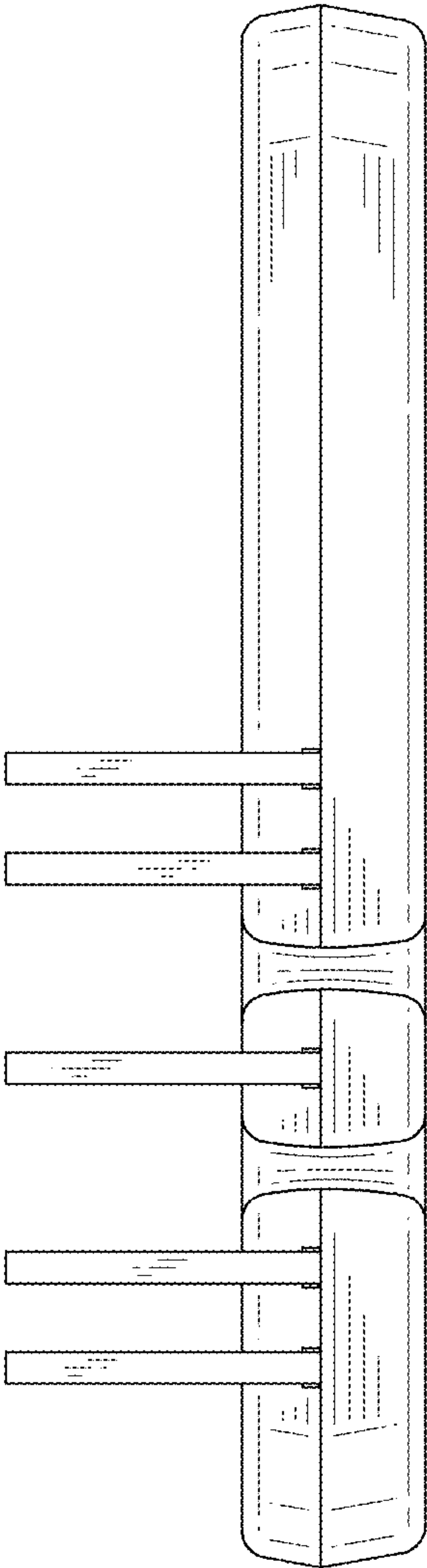


FIG.7

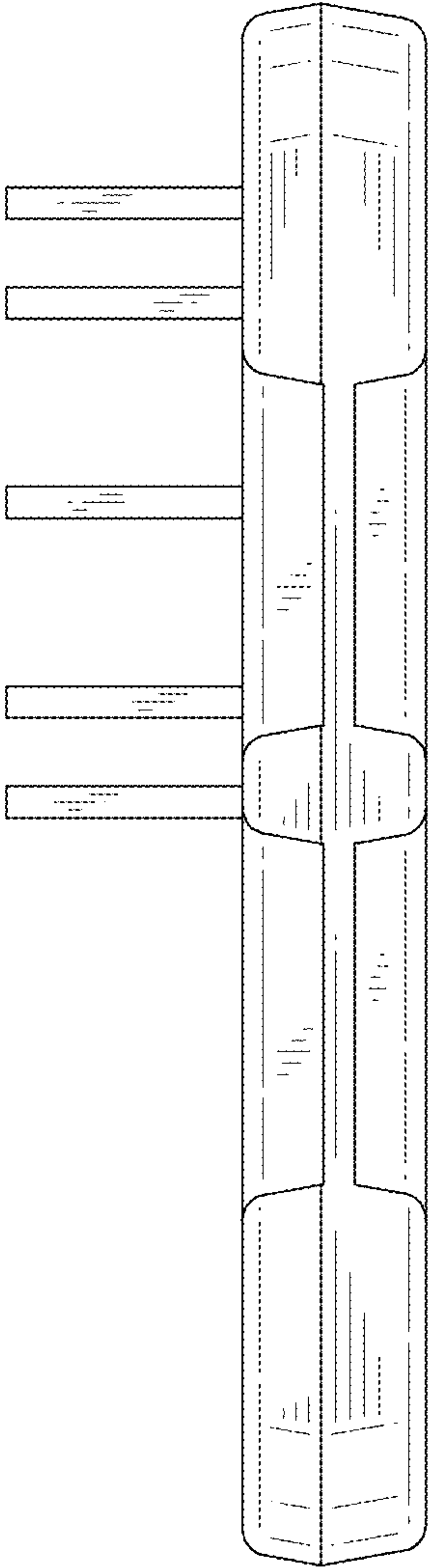


FIG.8

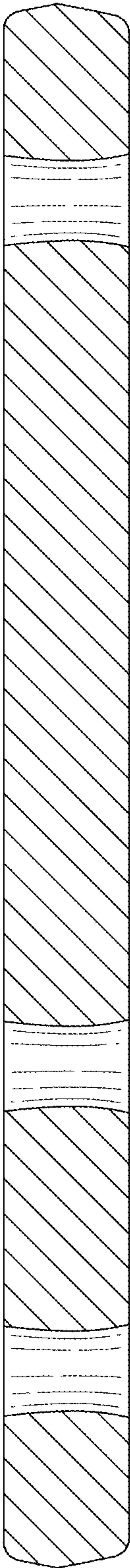


FIG.9

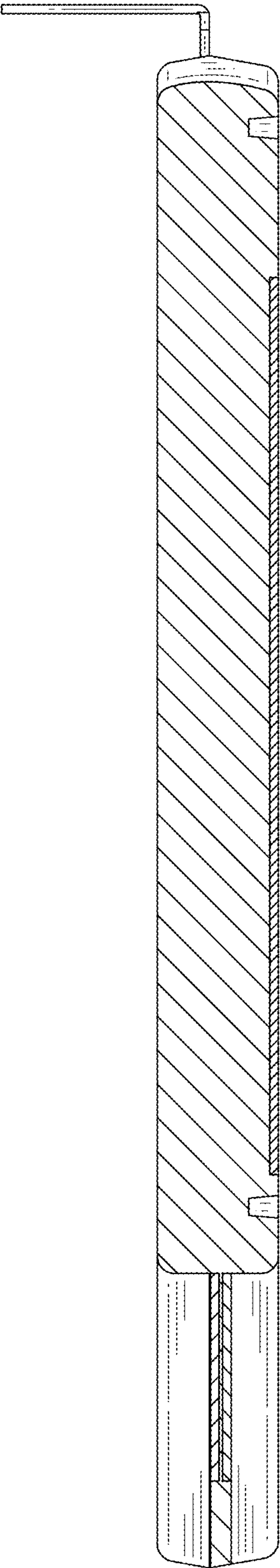


FIG.10

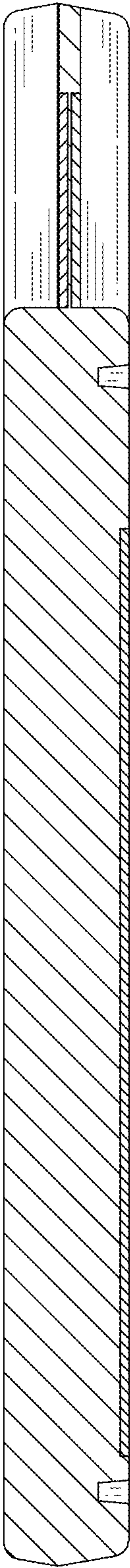


FIG.11

